

ABSTRACT

Provided are a film-like adhesive which can reduce the occurrence of voids even in a case in which curing is performed at a high temperature for a short period of time in multilevel lamination of semiconductor chips, a semiconductor package using the film-like adhesive, and a method for producing the semiconductor package. Disclosed is a film-like adhesive containing an epoxy resin (A), an epoxy resin curing agent (B), a phenoxy resin (C), and a silica filler (D), in which the content of the silica filler (D) is 30% to 70% by mass relative to the total amount of the epoxy resin (A), the epoxy resin curing agent (B), the phenoxy resin (C) and the silica filler (D), when the film-like adhesive is heated from room temperature at a rate of temperature increase of 5°C/min, the film-like adhesive exhibits a minimum melt viscosity in the range of 200 Pa·s to 10,000 Pa·s in a temperature range of higher than 120°C and 180°C or lower, and the gelation time at 180°C according to the hot plate method defined in JIS K6911 is 1 second to 200 seconds.